

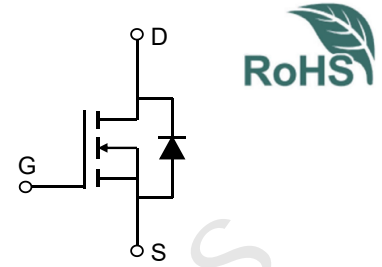
Description

Features

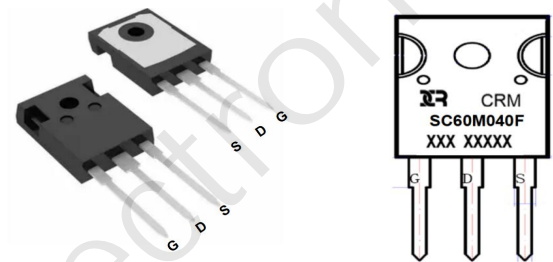
- 600V, 76A
 $R_{DS(ON)}$ Typ = 30mΩ @ $V_{GS} = 10V$
- Ultra-fast body diode
- Extremely low losses due to very low E_{on} and E_{off}
- Qualified for industrial grade applications according to JEDEC
- 100% avalanche tested

Application

- Uninterruptible Power Supply (UPS)
- Switch Mode Power Supply (SMPS)
- Power Factor Correction (PFC)



Schematic Diagram



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	TUBE(pcs)	InnerBox(pcs)	Per Carton (pcs)
CRMSC60M040F	CRMSC60M040F	TO-247-3L	TUBE	25	1000	2000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		600	V
V_{GS}	Gate-to-Source Voltage(static)		±20	V
V_{GS}	Gate-to-Source Voltage(dynamic)	AC(f>1 Hz)	±30	V
I_D	Continuous Drain Current ⁽¹⁾	$T_C = 25^\circ\text{C}$	76	A
		$T_C = 100^\circ\text{C}$	48	A
I_{DM}	Pulsed Drain Current ⁽²⁾	$T_C = 25^\circ\text{C}$	280	A
E_{AS}	Single Pulsed Avalanche Energy	$V_{DD}=50V; L=10mH$	480	mJ
I_S	Continuous diode forward current	$T_C = 25^\circ\text{C}$	76	A
$I_{S,pluse}$	Diode pluse current ⁽²⁾	$T_C = 25^\circ\text{C}$	280	A
diF/dt	Maximum diode commutation speed	$V_{DS}=0...400V, I_{SD} \leq 62A$	900	A/μs
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	-	W
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to- Ambient Device on PCB with Minimal footprint	-	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	-	°C/W

Electrical Characteristics ($T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 1\text{mA}, V_{GS} = 0\text{V}$	600	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 800\mu\text{A}$	2.7	3.5	4.3	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance	$V_{GS} = 10\text{V}, I_D = 29.5\text{A}$	-	30	37	mΩ
R_g	Gate resistance	$f = 1\text{MHz}, \text{opendrain}$	-	1	-	Ω

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 400\text{V},$ $f = 250\text{kHz}$	-	5200	-	pF
C_{oss}	Output Capacitance		-	105	-	pF
C_{rss}	Reverse Transfer Capacitance		-	10.0	-	pF
Q_g	Total Gate Charge		-	135	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10\text{V}$	-	32	-	nC
Q_{gd}	Gate Drain("Miller") Charge	$V_{DS} = 400\text{V}, I_D = 29.5\text{A}$	-	42	-	nC
$V_{plateau}$	Gate plateau voltage		-	5.2	-	V

Switching Characteristics

$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 13\text{V}, V_{DD} = 400\text{V}$ $I_D = 29.5\text{A}, R_G = 3.3\Omega$	-	25	-	ns
t_r	Turn-On Rise Time		-	21	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	110	-	ns
t_f	Turn-Off Fall Time		-	4	-	ns

Diode Recovery Characteristics

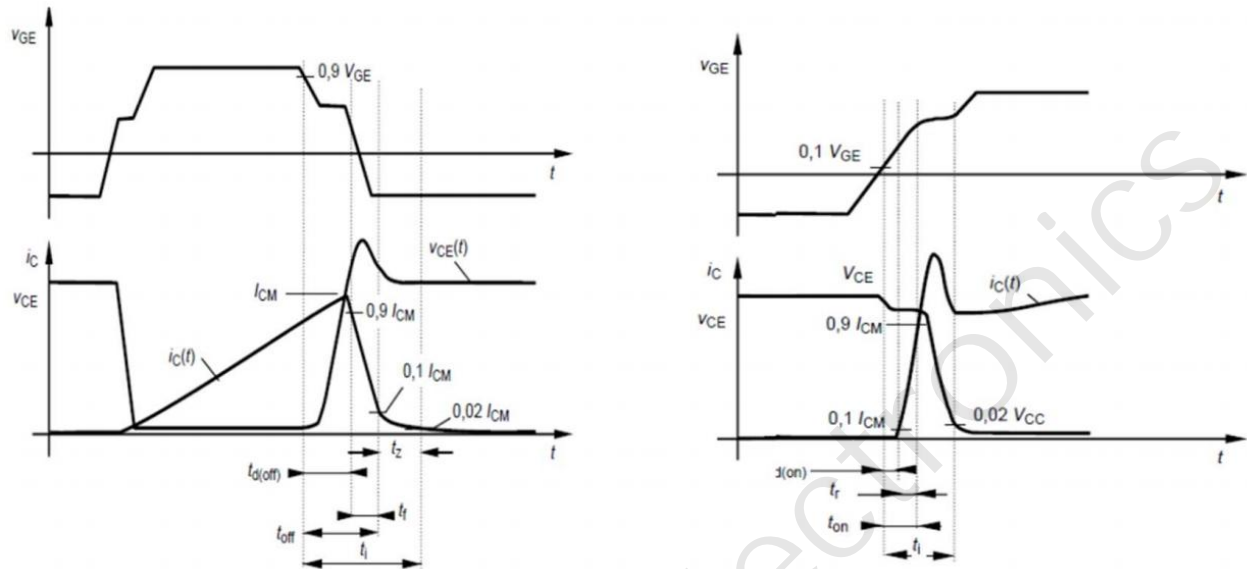
V_{SD}	Drain to Source Diode Forward Voltage		-	0.9	-	V
t_{rr}	Body Diode Reverse Recovery Time	$V_R = 400\text{V}, I_F = 8\text{A},$ $di/dt = 100\text{A/us}$	-	330	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	4.8	-	μC
I_{rrm}	Peak reverse recovery current		-	30	-	A

Notes:

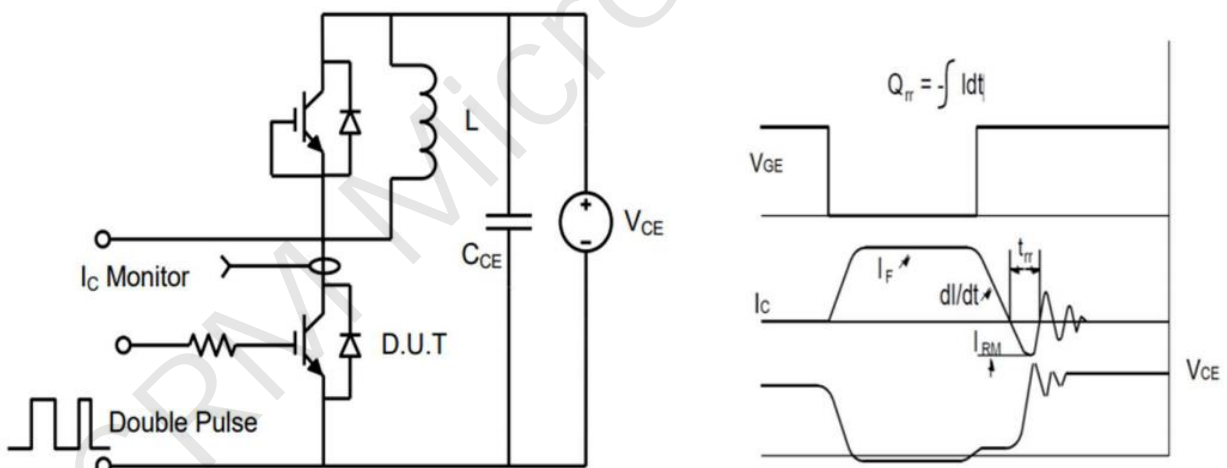
- Limited by $T_{j,max}$. Maximum Duty Cycle $D = 0.50$
- Repetitive Rating: Pulse width limited by maximum junction temperature

Test Circuit

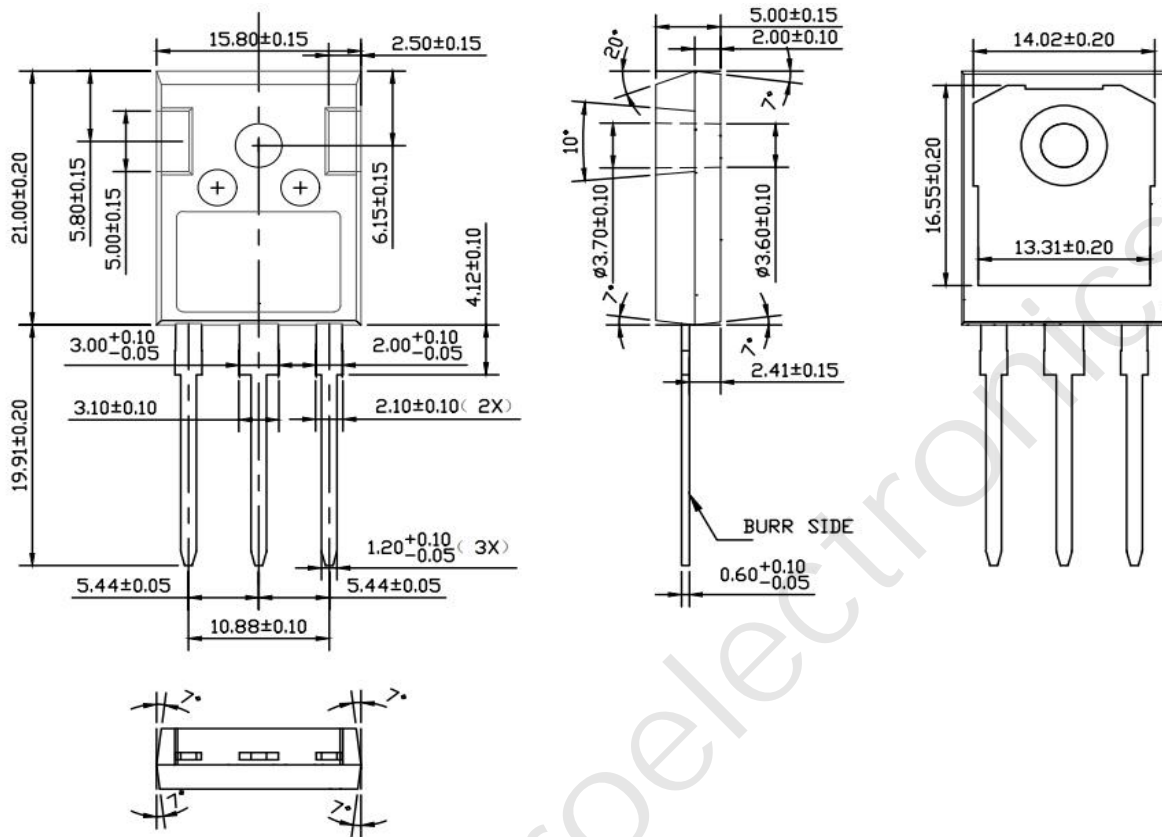
Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Mechanical Data(TO-247-3L)



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